## **Small Signal MOSFET**

# 20 V, 200 mA / -180 mA, Complementary, 1.0 x 1.0 mm SOT-963 Package

### **Features**

- Complementary MOSFET Device
- 1.5 V Gate Voltage Rating
- Ultra Thin Profile (< 0.5 mm) Allows It to Fit Easily into Extremely Thin Environments such as Portable Electronics.
- These are Pb-Free Devices

### **Applications**

- Load Switch with Level Shift
- Optimized for Power Management in Ultra Portable Equipment

### MAXIMUM RATINGS (T<sub>J</sub> = 25°C unless otherwise specified)

Para	Symbol	Value	Unit			
Drain-to-Source Voltage	$V_{DSS}$	20	V			
Gate-to-Source Voltag	je		V <sub>GS</sub>	±8	V	
N-Channel Continuous Drain	Steady	$T_A = 25^{\circ}C$		160		
Current (Note 1)	State	$T_A = 85^{\circ}C$		115		
	t ≤ 5 s	$T_A = 25^{\circ}C$		200	^	
P-Channel	Steady	T <sub>A</sub> = 25°C	I <sub>D</sub>	-140	mA	
Continuous Drain Current (Note 1)	State	T <sub>A</sub> = 85°C		-100		
	t ≤ 5 s	$T_A = 25^{\circ}C$		-180		
Power Dissipation (Note 1)	Steady State	T 0500		125	mW	
(14010-1)		$T_A = 25^{\circ}C$	$P_{D}$			
	t ≤ 5 s			200		
Pulsed Drain Current	N-Channel	t = 10 us	I <sub>DM</sub>	800	mA	
	P-Channel	t <sub>p</sub> = 10 μs		-600	IIIA	
Operating Junction and	T <sub>J</sub> , T <sub>STG</sub>	–55 to 150	°C			
Source Current (Body I	Is	200	mA			
Lead Temperature for S (1/8" from case for 1		oses	T <sub>L</sub>	260	°C	

Stresses exceeding Maximum Ratings may damage the device. Maximum Ratings are stress ratings only. Functional operation above the Recommended Operating Conditions is not implied. Extended exposure to stresses above the Recommended Operating Conditions may affect device reliability.

- Surface-mounted on FR4 board using the minimum recommended pad size, 1 oz. Cu.
- 2. Pulse Test: pulse width  $\leq$  300  $\mu$ s, duty cycle  $\leq$  2%

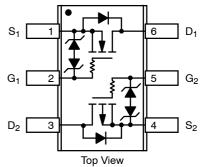


### ON Semiconductor®

### http://onsemi.com

V <sub>(BR)DSS</sub> R <sub>DS(on)</sub> Max		I <sub>D</sub> Max
	5.0 Ω @ -4.5 V	
P-Channel -20 V	7.0 Ω @ -2.5 V	-0.18 A
	10 Ω @ -1.8 V	-0.16 A
	14 Ω @ -1.5 V	
	3.0 Ω @ 4.5 V	
N-Channel 20 V	4.0 Ω @ 2.5 V	0.20 A
	6.0 Ω @ 1.8 V	0.20 A
	10 Ω @ 1.5 V	

### PINOUT: SOT-963





SOT-963 CASE 527AA



SM

S = Specific Device Code

M = Date Code

### **ORDERING INFORMATION**

Device	Package	Shipping <sup>†</sup>
NTUD3127CT5G	SOT-963 (Pb-Free)	8000 / Tape & Reel

†For information on tape and reel specifications, including part orientation and tape sizes, please refer to our Tape and Reel Packaging Specifications Brochure, BRD8011/D.

### THERMAL RESISTANCE RATINGS

Parameter	Symbol	Max	Unit
Junction-to-Ambient - Steady State, Minimum Pad (Note 3)	$R_{ hetaJA}$	1000	°C/W
$Junction-to-Ambient - t \le 5 s \text{ (Note 3)}$		600	

<sup>3.</sup> Surface-mounted on FR4 board using the minimum recommended pad size, 1 oz. Cu.

### **ELECTRICAL CHARACTERISTICS** (T<sub>1</sub> = 25°C unless otherwise specified)

Parameter	Symbol	N/P	Test Condition		Min	Тур	Max	Unit	
OFF CHARACTERISTICS									
Drain-to-Source Breakdown Voltage	.,	N	V <sub>GS</sub> = 0 V	I <sub>D</sub> = 250 μA	20			.,	
	$V_{(BR)DSS}$	Р		I <sub>D</sub> = -250 μA	-20			V	
Zero Gate Voltage Drain Current				., .,,, -,,,	T <sub>J</sub> = 25°C			50	
		N	$V_{GS} = 0 \text{ V}, V_{DS} = 5.0 \text{ V}$	T <sub>J</sub> = 85°C			200		
	I <sub>DSS</sub>		., .,,,,	T <sub>J</sub> = 25°C			-50	nA	
		Р	$V_{GS} = 0 \text{ V}, V_{DS} = -5.0 \text{ V}$	T <sub>J</sub> = 85°C			-200		
Zero Gate Voltage Drain Current				100					
	I <sub>DSS</sub>	Р	V <sub>GS</sub> = 0 V, V <sub>DS</sub> = -16 V	$V_{GS} = 0 \text{ V}, V_{DS} = -16 \text{ V}$ $T_J = 25^{\circ}\text{C}$			-100	nA	
Gate-to-Source Leakage Current		N	., .,	.5.01/			100		
	I <sub>GSS</sub>	Р	$V_{DS} = 0 V, V_{GS} =$	±5.0 V			-100	nA	
ON CHARACTERISTICS (Note 4)									
Gate Threshold Voltage	.,	N	$V_{GS} = V_{DS}$	I <sub>D</sub> = 250 μA	0.4		1.0	V	
	$V_{GS(TH)}$	Р		I <sub>D</sub> = -250 μA	-0.4		-1.0		
Drain-to-Source On Resistance	N		V <sub>GS</sub> = 4.5 V, I <sub>D</sub> = 100 mA			1.5	3.0		
	R <sub>DS(on)</sub>	Р	V <sub>GS</sub> = -4.5V, I <sub>D</sub> = -	$V_{GS} = -4.5V$ , $I_D = -100 \text{ mA}$		4.0	5.0	Ω	
		N	V <sub>GS</sub> = 2.5 V, I <sub>D</sub> =	$V_{GS} = 2.5 \text{ V}, I_D = 50 \text{ mA}$		2.0	4.0		
		Р	$V_{GS} = -2.5V$ , $I_D = -50$ mA			5.0	7.0		
		N	V <sub>GS</sub> = 1.8 V, I <sub>D</sub> = 20 mA			3.0	6.0		
		Р	$V_{GS} = -1.8V$ , $I_D = -20 \text{ mA}$			6.5	10		
		N	V <sub>GS</sub> = 1.5 V, I <sub>D</sub> = 10 mA			4.0	10		
		Р	$V_{GS} = -1.5 \text{ V}, I_D = -10 \text{ mA}$			7.5	14		
		N	V <sub>GS</sub> = 1.2 V, I <sub>D</sub> =	1.0 mA		5.5			
		Р	$V_{GS} = -1.2 \text{ V}, I_D = -1.2 \text{ V}$	-1.0 mA		11.5			
Forward Transconductance	_	N	$V_{DS} = 5.0 \text{ V}, I_D = 1$	25 mA		0.35			
	9FS	Р	$V_{DS} = -5.0 \text{ V}, I_D = -125 \text{ mA}$			0.26		S	
CHARGES, CAPACITANCES AND GA	TE RESISTA	NCE							
Input Capacitance	C <sub>ISS</sub>					9.0			
Output Capacitance	C <sub>OSS</sub>	N	f = 1 MHz, V <sub>GS</sub> : V <sub>DS</sub> = 15 V	= 0 V		3.0		1	
Reverse Transfer Capacitance	C <sub>RSS</sub>	1	. 50			2.2		~_	
Input Capacitance	C <sub>ISS</sub>					12		pF	
Output Capacitance	C <sub>OSS</sub>	Р	f = 1 MHz, V <sub>GS</sub> : V <sub>DS</sub> = -15 \	= 0 V /		2.7			
Reverse Transfer Capacitance	C <sub>RSS</sub>		100 10			1.0			

<sup>4.</sup> Switching characteristics are independent of operating junction temperatures

### **ELECTRICAL CHARACTERISTICS** (T<sub>J</sub> = 25°C unless otherwise specified)

Parameter	Symbol	N/P	Test Condition	on	Min	Тур	Max	Unit
SWITCHING CHARACTERISTICS, V <sub>GS</sub> = 4.5 V (Note 4)								
Turn-On Delay Time	t <sub>d(ON)</sub>					15		
Rise Time	t <sub>r</sub>	١.,	V <sub>GS</sub> = 4.5 V, V <sub>DD</sub> = 10 V,		24			
Turn-Off Delay Time	t <sub>d(OFF)</sub>	N	$R_G = 2.0 \Omega$			90		
Fall Time	t <sub>f</sub>					60		
Turn-On Delay Time	t <sub>d(ON)</sub>		$V_{GS} = -4.5 \text{ V}, V_{DD} = -15 \text{ V},$ $I_{D} = -180 \text{ mA}, R_{G} = 2.0 \Omega$			20		ns
Rise Time	t <sub>r</sub>	P				37		
Turn-Off Delay Time	t <sub>d(OFF)</sub>	7 "				112		
Fall Time	t <sub>f</sub>					97		
DRAIN-SOURCE DIODE CHARACTERISTICS								
Forward Diode Voltage	V	N	V <sub>GS</sub> = 0 V, I <sub>S</sub> = 10 mA	T 0500		0.60	1.0	\ <i>/</i>
	V <sub>SD</sub>	Р	$V_{GS} = 0 \text{ V}, I_{S} = -10 \text{ mA}$	T <sub>J</sub> = 25°C		-0.65	-1.0	V

<sup>4.</sup> Switching characteristics are independent of operating junction temperatures

### TYPICAL PERFORMANCE CURVES - N-CHANNEL

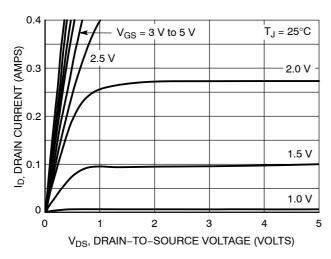


Figure 1. On-Region Characteristics

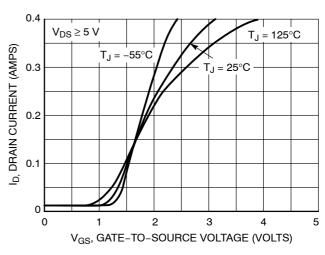


Figure 2. Transfer Characteristics

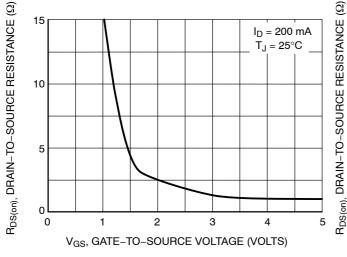


Figure 3. On-Resistance vs. Gate Voltage

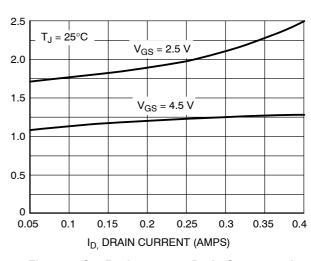


Figure 4. On-Resistance vs. Drain Current and Gate Voltage

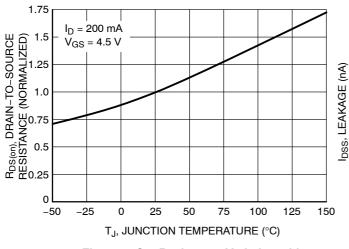


Figure 5. On–Resistance Variation with Temperature

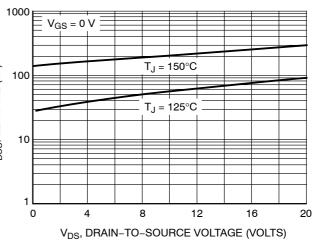


Figure 6. Drain-to-Source Leakage Current vs. Voltage

### **TYPICAL PERFORMANCE CURVES - N-CHANNEL**

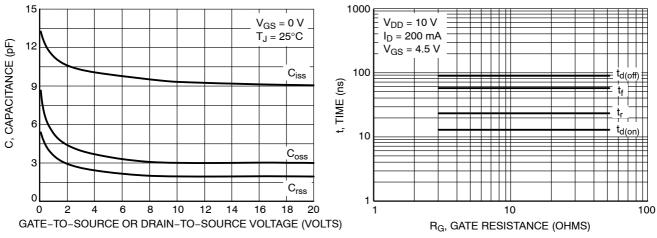


Figure 7. Capacitance Variation

Figure 8. Resistive Switching Time Variation vs. Gate Resistance

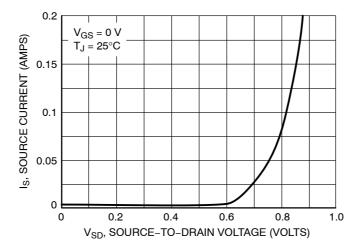


Figure 9. Diode Forward Voltage vs. Current

### TYPICAL PERFORMANCE CURVES - P-CHANNEL

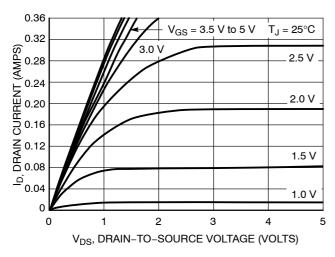


Figure 10. On-Region Characteristics

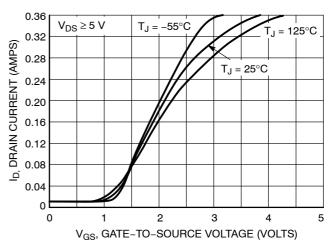


Figure 11. Transfer Characteristics

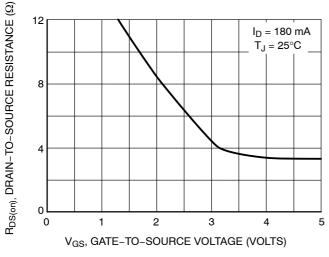


Figure 12. On-Resistance vs. Gate Voltage

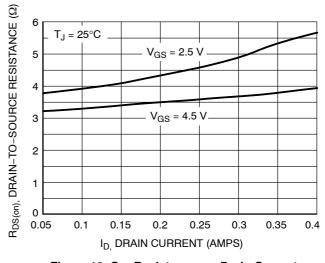


Figure 13. On-Resistance vs. Drain Current and Gate Voltage

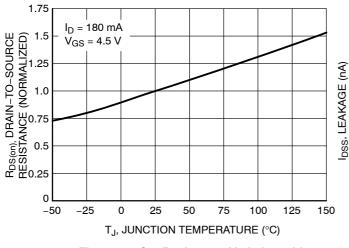


Figure 14. On–Resistance Variation with Temperature

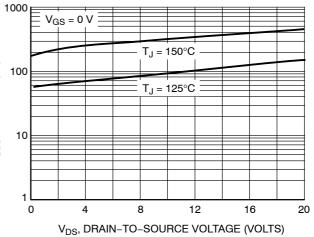


Figure 15. Drain-to-Source Leakage Current vs. Voltage

### **TYPICAL PERFORMANCE CURVES - P-CHANNEL**

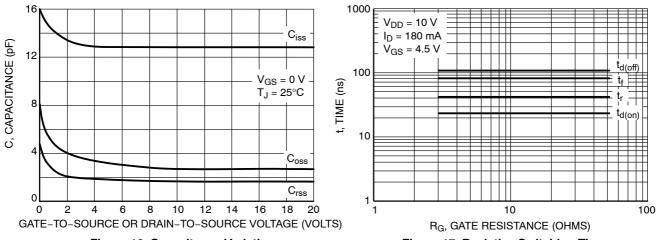


Figure 16. Capacitance Variation

Figure 17. Resistive Switching Time Variation vs. Gate Resistance

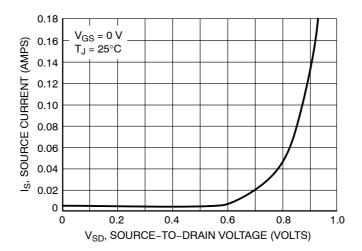


Figure 18. Diode Forward Voltage vs. Current

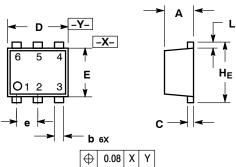
STYLE 10:

PIN 1. CATHODE 1 2. N/C 3. CATHODE 2 4. ANODE 2 5. N/C 6. ANODE 1



SOT-963 CASE 527AA-01 ISSUE D

**DATE 30 JUL 2008** 



<b>←</b> D →	_Y_	
	-X-	
6 5 4	↑ [	<b>─</b>
	E	HE
01 2 3	<u></u>	<b></b>   ↓
→ e ←	С	
<b>→</b>	← b 6X	
	⊕ 0.08 X Y	

2. BASE 1 3. COLLECTOR 2 4. EMITTER 2 5. BASE 2 6. COLLECTOR 1	STYLE 2: PIN 1. EMITTER 1 2. EMITTER2 3. BASE 2 4. COLLECTOR 2 5. BASE 1 6. COLLECTOR 1	<ol> <li>CATHODE 1</li> <li>ANODE/ANODE 2</li> <li>CATHODE 2</li> <li>CATHODE 2</li> <li>ANODE/ANODE 1</li> </ol>
2. COLLECTOR 3. BASE 4. EMITTER 5. COLLECTOR	STYLE 5: PIN 1. CATHODE 2. CATHODE 3. ANODE 4. ANODE 5. CATHODE 6. CATHODE	2. ANODE 3. CATHODE 4. CATHODE 5. CATHODE
STYLE 7: PIN 1. CATHODE 2. ANODE 3. CATHODE 4. CATHODE 5. ANODE 6. CATHODE	STYLE 8: PIN 1. DRAIN 2. DRAIN 3. GATE 4. SOURCE 5. DRAIN 6. DRAIN	STYLE 9: PIN 1. SOURCE 1 2. GATE 1 3. DRAIN 2 4. SOURCE 2 5. GATE 2 6. DRAIN 1

#### NOTES:

- 1. DIMENSIONING AND TOLERANCING PER ANSI
- Y14.5M, 1982. CONTROLLING DIMENSION: MILLIMETERS
- MAXIMUM LEAD THICKNESS INCLUDES LEAD FINISH THICKNESS. MINIMUM LEAD THICKNESS IS THE MINIMUM THICKNESS OF BASE MATERIAL.

		MII	LIMETE	RS		INCHES	
Į	DIM	MIN	NOM	MAX	MIN	MON	MAX
	Α	0.40	0.45	0.50	0.016	0.018	0.020
	b	0.10	0.15	0.20	0.004	0.006	0.008
	С	0.05	0.10	0.15	0.002	0.004	0.006
	D	0.95	1.00	1.05	0.037	0.039	0.041
	Е	0.75	0.80	0.85	0.03	0.032	0.034
	е		0.35 BS	С	(	0.014 BS	C
	L	0.05	0.10	0.15	0.002	0.004	0.006
	Hε	0.95	1.00	1.05	0.037	0.039	0.041

### **GENERIC MARKING DIAGRAM\***

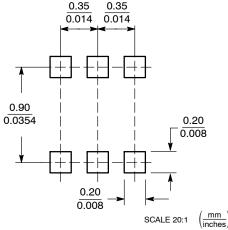


= Specific Device Code Χ

= Month Code Μ

\*This information is generic. Please refer to device data sheet for actual part marking.

Pb-Free indicator, "G" or microdot " ■", may or may not be present.
SOLDERING FOOTPRINT\*



\*For additional information on our Pb-Free strategy and soldering details, please download the ON Semiconductor Soldering and Mounting Techniques Reference Manual, SOLDERRM/D.

DOCUMENT NUMBER:	98AON18698D	Electronic versions are uncontrolled except when accessed directly from the Document Rep Printed versions are uncontrolled except when stamped "CONTROLLED COPY" in red.			
DESCRIPTION:	SOT-963, 1X1, 0.35P		PAGE 1 OF 1		

ON Semiconductor and unare trademarks of Semiconductor Components Industries, LLC dba ON Semiconductor or its subsidiaries in the United States and/or other countries. ON Semiconductor reserves the right to make changes without further notice to any products herein. ON Semiconductor makes no warranty, representation or guarantee regarding the suitability of its products for any particular purpose, nor does ON Semiconductor assume any liability arising out of the application or use of any product or circuit, and specifically disclaims any and all liability, including without limitation special, consequential or incidental damages. ON Semiconductor does not convey any license under its patent rights nor the rights of others.

onsemi, ONSEMI., and other names, marks, and brands are registered and/or common law trademarks of Semiconductor Components Industries, LLC dba "onsemi" or its affiliates and/or subsidiaries in the United States and/or other countries. onsemi owns the rights to a number of patents, trademarks, copyrights, trade secrets, and other intellectual property. A listing of onsemi's product/patent coverage may be accessed at <a href="www.onsemi.com/site/pdf/Patent\_Marking.pdf">www.onsemi.com/site/pdf/Patent\_Marking.pdf</a>. Onsemi reserves the right to make changes at any time to any products or information herein, without notice. The information herein is provided "as-is" and onsemi makes no warranty, representation or guarantee regarding the accuracy of the information, product features, availability, functionality, or suitability of its products for any particular purpose, nor does onsemi assume any liability arising out of the application or use of any product or circuit, and specifically disclaims any and all liability, including without limitation special, consequential or incidental damages. Buyer is responsible for its products and applications using onsemi products, including compliance with all laws, regulations and safety requirements or standards, regardless of any support or applications information provided by onsemi. "Typical" parameters which may be provided in onsemi data sheets and/or specifications can and do vary in different applications and actual performance may vary over time. All operating parameters, including "Typicals" must be validated for each customer application by customer's technical experts. onsemi does not convey any license under any of its intellectual property rights nor the rights of others. onsemi products are not designed, intended, or authorized for use as a critical component in life support systems or any EDA class 3 medical devices or medical devices with a same or similar classification in a foreign jurisdiction or any devices intended for implantation in the human body. Sh

#### **PUBLICATION ORDERING INFORMATION**

LITERATURE FULFILLMENT: Email Requests to: orderlit@onsemi.com

onsemi Website: www.onsemi.com

TECHNICAL SUPPORT North American Technical Support: Voice Mail: 1 800-282-9855 Toll Free USA/Canada Phone: 011 421 33 790 2910

Europe, Middle East and Africa Technical Support:

Phone: 00421 33 790 2910

For additional information, please contact your local Sales Representative